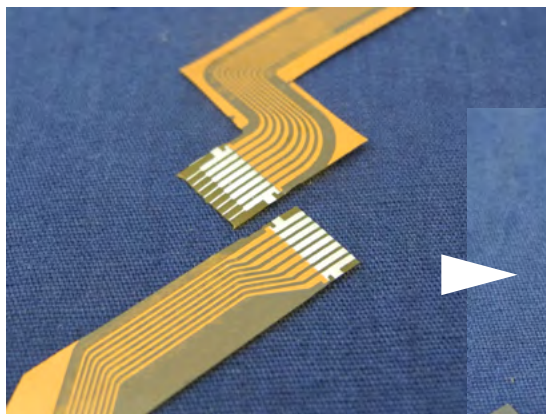




# SoundBonding application

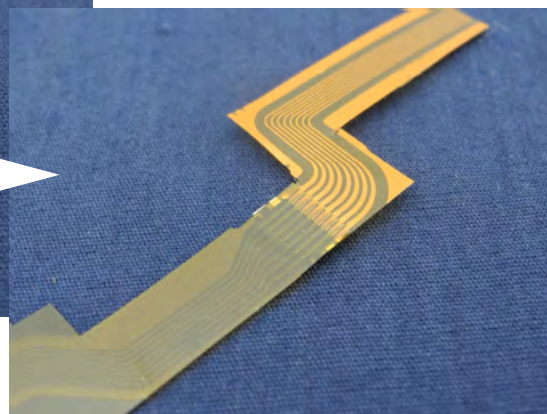


## 〈FPCのクリップ合金 音波接合〉

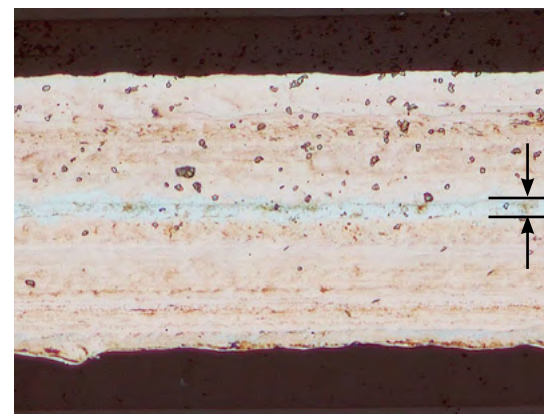


[接合前]

- 銅回路厚さ：約 50  $\mu\text{m}$
- ハンダメッキ厚さ：10  $\mu\text{m}$

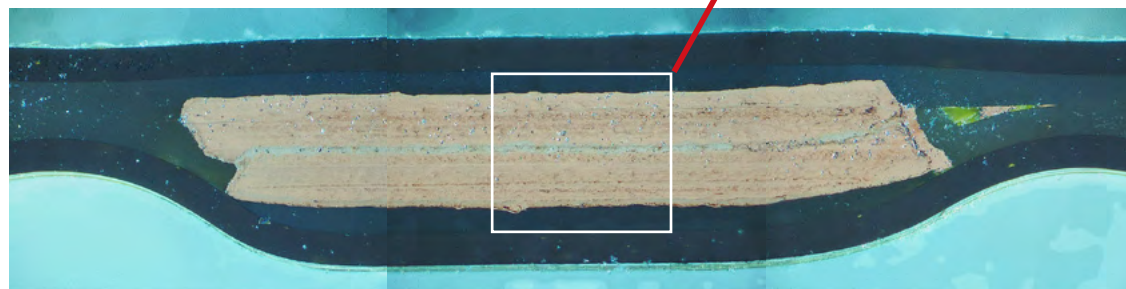


[接合後]



- ハンダメッキ接合部  
厚さ：約 6.5  $\mu\text{m}$

[接合部断面拡大 x1750]



[接合部断面]

**ULTEX**  
SoundPower Laboratory